

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die		Lead Dioxide (PbO2)	1309-60-0	0.00237	1.27	0.03556
	Doped silicon	Silicon (Si)	7440-21-3	0.1844	98.73	2.76444
<b>Subtotal</b>				<b>0.18677</b>	<b>100</b>	<b>2.8</b>
Post-plating	Pure metal	Tin (Sn)	7440-31-5	0.34465	100.0	5.167
<b>Subtotal</b>				<b>0.34465</b>	<b>100</b>	<b>5.167</b>
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.0098	0.03	0.14694
	Pure metal layer	Zinc (Zn)	7440-66-6	0.00653	0.02	0.09796
	Pure metal layer	Tin (Sn)	7440-31-5	0.0098	0.03	0.14694
	Pure metal layer	Iron (Fe)	7439-89-6	0.03594	0.11	0.53877
	Pure metal layer	Copper (Cu)	7440-50-8	32.60827	99.81	488.8594
<b>Subtotal</b>				<b>32.67034</b>	<b>100</b>	<b>489.79001</b>
Mould Compound	Additive	Cristobalite	14464-46-1	0.33299	0.5	4.9922
	Filler	Silica fused	60676-86-0	54.61094	82.0	818.7208
	Polymer	Phenolic resin		3.32994	5.0	49.922
	Flame retardant	Metal hydroxide		2.66395	4.0	39.9376
	Pigment	Carbon black	1333-86-4	0.33299	0.5	4.9922
	Polymer	Epoxy resin system		5.3279	8.0	79.8752
<b>Subtotal</b>				<b>66.59871</b>	<b>100</b>	<b>998.44</b>
Solder Wire	Tin alloy	Tin (Sn)	7440-31-5	0.01079	10.0	0.16171
	Silver alloy	Silver (Ag)	7440-22-4	0.00216	2.0	0.03234
	Lead alloy	Lead (Pb)	7439-92-1	0.09492	88.0	1.42303
<b>Subtotal</b>				<b>0.10787</b>	<b>100</b>	<b>1.61708</b>
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.09166	100.0	1.37413
<b>Subtotal</b>				<b>0.09166</b>	<b>100</b>	<b>1.37413</b>
<b>Total</b>				<b>100</b>	<b>100</b>	<b>1499.18822</b>

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